5NM90 **Power MOSFET Preliminary**

5A, 900V N-CHANNEL SUPER-JUNCTION MOSFET

DESCRIPTION

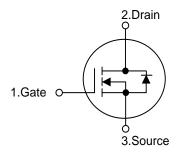
The UTC 5NM90 is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

FEATURES

- * $R_{DS(ON)} \le 2.5 \Omega$ @ $V_{GS}=10V$, $I_D=2.5A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness

TO-220 TO-220F1 TO-220F2 TO-251 TO-251S2 TO-252

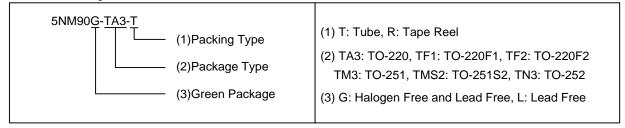
SYMBOL



ORDERING INFORMATION

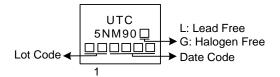
Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
5NM90L-TA3-T	5NM90G-TA3-T	TO-220	G	D	S	Tube	
5NM90L-TF1-T	5NM90G-TF1-T	TO-220F1	G	D	S	Tube	
5NM90L-TF2-T	5NM90G-TF2-T	TO-220F2	G	D	S	Tube	
5NM90L-TM3-T	5NM90G-TM3-T	TO-251	G	D	S	Tube	
5NM90L-TMS2-T	5NM90G-TMS2-T	TO-251S2	G	D	S	Tube	
5NM90L-TN3-R	5NM90G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ MARKING



■ **ABSOLUTE MAXIMUM RATINGS** (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	900	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Continuous Drain Current	Continuous	I_{D}	5.0	Α	
Pulsed Drain Current	Pulsed (Note 2)	I_{DM}	20	Α	
Avalanche Current (Note 2)		I _{AR}	1.5	Α	
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	179	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.6	V/ns	
	TO-220		45	W	
Dawar Dissipation	TO-220F1/TO-220F2	Б	25	W	
Power Dissipation	TO-251S2/TO-251	P_D	0.7	107	
	TO-252		37	W	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 159mH, I_{AS} = 1.5A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C.
- 4. $I_{SD} \le 5.0 A$, di/dt $\le 200 A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25 ^{\circ}C$.

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT	
Junction to Ambient	TO-220/TO-220F1 TO-220F2	0	62.5	°C/W	
	TO-251S2/TO-251 TO-252	$ heta_{JA}$	110	°C/W	
Junction to Case	TO-220	-220 2.78		°C/W	
	TO-220F1/TO-220F2	0	5	°C/W	
	TO-251S2/TO-251 TO-252	$ heta_{ extsf{JC}}$	3.38 (Note)	°C/W	

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

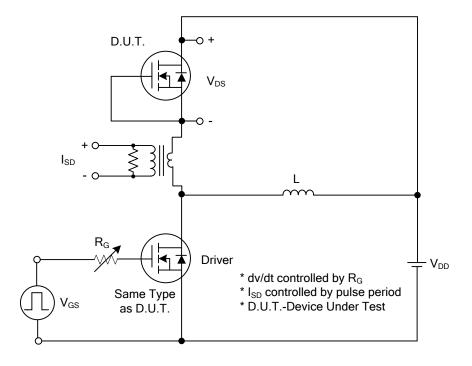
■ **ELECTRICAL CHARACTERISTICS** (T_J =25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage		BV _{DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	900			V	
Drain-Source Leakage Current		I _{DSS}	$V_{DS} = 900V, V_{GS} = 0V$			10	μA	
Gate-Source Leakage Current	Forward		$V_{GS} = 30V, V_{DS} = 0V$			100	nA	
	Reverse	I_{GSS}	$V_{GS} = -30V, V_{DS} = 0V$			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		V _{GS(TH)}	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.5		4.5	V	
Static Drain-Source On-State Resistance		R _{DS(ON)}	$V_{GS} = 10V, I_D = 2.5A$			2.5	Ω	
DYNAMIC CHARACTERISTICS								
Input Capacitance	nput Capacitance				380		pF	
Output Capacitance		Coss	$V_{GS}=0V$, $V_{DS}=25V$, $f=1.0MHz$		160		pF	
Reverse Transfer Capacitance		C _{RSS}			8		рF	
SWITCHING CHARACTERISTICS								
Total Gate Charge (Note 1)		Q_G	V _{DS} =50V, I _D =1.3A, I _G =100μA		47		nC	
Gate to Source Charge		Q_GS	V _{GS} =10V (Note 1,2)		4		nC	
Gate to Drain Charge		Q_{GD}	VGS=10V (Note 1,2)		12		nC	
Turn-ON Delay Time (Note 1)		t _{D(ON)}			40		nS	
Rise Time		t _R	V_{DD} =30V, I_{D} =0.5A, R_{G} =25 Ω ,		70		nS	
Turn-OFF Delay Time		t _{D(OFF)}	V _{GS} =10V (Note 1,2)		180		nS	
Fall-Time		t _F			45		nS	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous Current		Is				5.0	Α	
Maximum Body-Diode Pulsed Current		I _{SM}				20	Α	
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I _S =5.0A, V _{GS} =0V			1.4	V	
Body Diode Reverse Recovery Time (Note 1)		t _{rr}	I _S =5.0A, V _{GS} =0V,		520		nS	
Body Diode Reverse Recovery Charge		Qrr	dI _F /dt=100A/μs		4.65		μC	

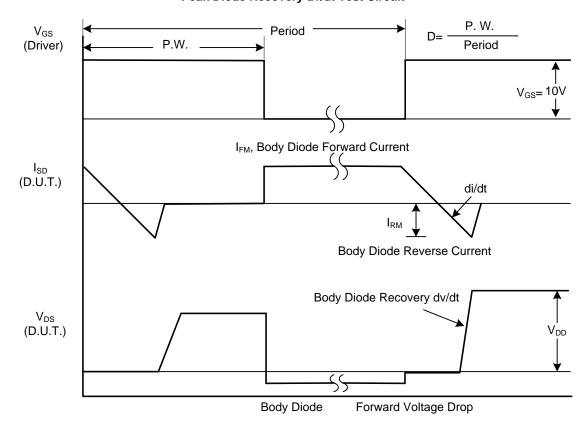
Notes: 1. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%.

^{2.} Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

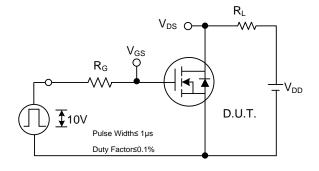


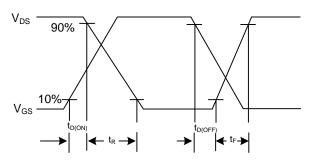
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

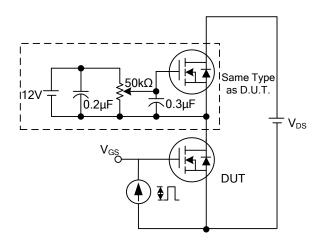
■ TEST CIRCUITS AND WAVEFORMS (Cont.)

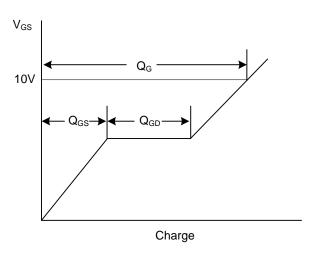




Switching Test Circuit

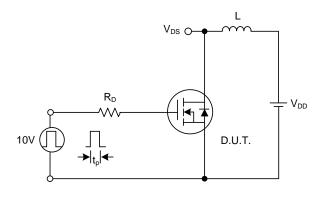
Switching Waveforms

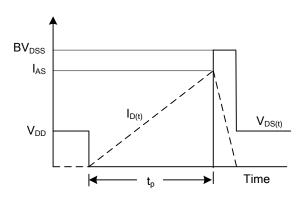




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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